TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (Ultra-High-Speed U-MOSIII)

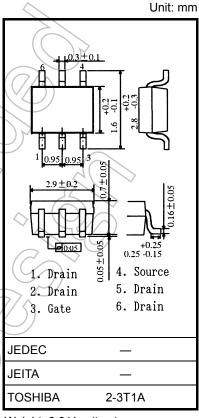
TPC6006-H

Notebook PC Applications Portable Equipment Applications

- Small footprint due to small and thin package
- High-speed switching
- Small gate charge: Qsw = 2.4 nC (typ.)
- Low drain-source ON-resistance: RDS (ON) = 59 m Ω (typ.)
- High forward transfer admittance: $|Y_{fs}| = 7 S$ (typ.)
- Low leakage current: $I_{DSS} = 10 \mu A \text{ (max) (V}_{DS} = 40 \text{ V)}$
- Enhancement mode: $V_{th} = 1.1$ to 2.3 V ($V_{DS} = 10$ V, $I_{D} = 1$ mA)

Absolute Maximum Ratings (Ta = 25°C)

Characteristics		Symbol	Rating	Unit
Drain-source voltage		V_{DSS}	40	> V
Drain-gate voltage (RG	$S = 20 \text{ k}\Omega$)	V_{DGR}	40	V
Gate-source voltage		V_{GSS}	±20	V
Drain current	DC (Note 1)	ID 〈	3.9	A
Diain current	Pulse (Note 1)	IDP	15.6	
Drain power dissipation	(t = 5 s) (Note 2a)	PD	2.2	w
Drain power dissipation (t = 5 s) (Note 2b)		(PD)	0.7	w
Single pulse avalanche energy (Note 3)		EAS	7	r _m
Avalanche current		Y _{AR}	3.9	Α
Repetitive avalanche energy (Note 4)		EAR	0.22	mJ
Channel temperature		T _{ch}	150	°C
Storage temperature ra	nge	T _{stg}	-55 to 150	°C



Weight: 0.011 g (typ.)

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/ "Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

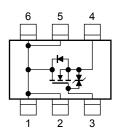
Thermal Characteristics

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to ambient (t = 5 s) (Note 2a)	R _{th (ch-a)}	56.8	°C/W
Thermal resistance, channel to ambient (t = 5 s) (Note 2b)	R _{th (ch-a)}	178.5	°C/W

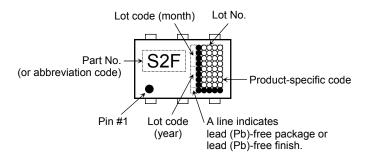
Note: (Note 1), (Note 2), (Note 3), (Note 4) and (Note 5): See the next page.

This transistor is an electrostatic-sensitive device. Handle with care.

Circuit Configuration



Marking (Note 5)



Electrical Characteristics (Ta = 25°C)

Gate leakage current IGSS								
Drain cut-OFF current Drain cut-OFF cutrent Dra	Char	racteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Drain-source breakdown voltage V (BR) DSS ID = 10 mA, VGS = 0 V 40	Gate leakage curre	ent	I _{GSS}	$V_{GS} = \pm 16 \text{ V}, V_{DS} = 0 \text{ V}$	- /	\ <u>\</u>	±10	μА
Drain-source breakdown voltage V (BR) DSX D = 10 mA, V _{GS} = -20 V 25	Drain cut-OFF curi	rent	I _{DSS}	$V_{DS} = 40 \text{ V}, V_{GS} = 0 \text{ V}$	4		> 10	μΑ
V (BR) DSX ID = 10 mA, VGS = -20 V 25	Drain-source breat	kdown voltage	V _{(BR) DSS}	$I_D = 10 \text{ mA}, V_{GS} = 0 \text{ V}$	40	(4)) —	V
Drain-source ON resistance RDS (ON) VGS = 4.5 V, ID = 1.9 A 78 100 MCS = 10 V, ID = 1.9 A 59 75 MCS = 10 V, ID = 1.9 A 59 75 MCS = 10 V, ID = 1.9 A 3.5 7 — S Input capacitance Ciss	Drain-source breakdown voltage		V _{(BR)DSX}	$I_D = 10 \text{ mA}, V_{GS} = -20 \text{ V}$	25		_	V
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	Gate threshold vol	tage	V_{th}	$V_{DS} = 10 \text{ V}, I_{D} = 1 \text{ mA}$	T	<u> </u>	2.3	٧
Forward transfer admittance $ Y_{fs} $ $V_{DS} = 10 \text{ V}, I_D = 1.9 \text{ A}$ $0.59 75$ $0.59 75$ $0.59 10 \text{ V}, I_D = 1.9 \text{ A}$ $0.59 75$ $0.59 10 \text{ V}, I_D = 1.9 \text{ A}$ $0.55 7$ $0.59 10 \text{ V}, I_D = 1.9 \text{ A}$ $0.55 7$ $0.59 10 \text{ V}, I_D = 1.9 \text{ A}$ $0.55 7$ $0.59 10 \text{ V}, I_D = 1.9 \text{ A}$ $0.55 7$ $0.59 10 \text{ V}, I_D = 1.9 \text{ A}$ $0.59 $	Drain-source ON r	esistance	Rpc (ON)	$V_{GS} = 4.5 \text{ V}, I_D = 1.9 \text{ A}$		78	100	mO
Input capacitance C_{iss} C_{iss			NDS (ON)	$V_{GS} = 10 \text{ V}, I_D = 1.9 \text{ A}$) —	59	75	1112.2
Reverse transfer capacitance O_{CSS} $V_{DS} = 10 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$ -18 -1	Forward transfer a	dmittance	Y _{fs}	$V_{DS} = 10 \text{ V}, I_D = 1.9 \text{ A}$	3.5	7		S
Output capacitance C_{OSS} $ 73$ $ -$	Input capacitance		C _{iss}			251		
	Reverse transfer c	apacitance	C _{rss}	$V_{DS} = 10 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		18		pF
Switching time $ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	Output capacitance		Coss			73		
Switching time $ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	Switching time	Rise time	(H)	VGS 0 V VOUT		4		
		Turn-ON time	ton			9		
		Fall time	t _f		_	3		ns
$Q_{g} \begin{tabular}{ c c c c c c c c c c c c c c c c c c c$		Turn-OFF time	toff	V _{DD} ≃ 20 V	_	18		
$V_{DD} \simeq 32 \text{ V, } V_{GS} = 5 \text{ V, } I_D = 3.9 \text{ A} \qquad \qquad 2.4 \qquad -$ Gate-source charge 1 $Q_{gs1} \qquad \qquad - \qquad 1.0 \qquad -$ Gate-drain ("Miller") charge $Q_{gd} \qquad V_{DD} \simeq 32 \text{ V, } V_{GS} = 10 \text{ V, } I_D = 3.9 \text{ A} \qquad \qquad 0.8 \qquad -$			∕ O _a	$V_{DD} \simeq 32 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 3.9 \text{ A}$		4.4		
$ \begin{array}{c ccccccccccccccccccccccccccccccccccc$	(gate-source plus gate-drain)		d ag	$V_{DD} \simeq 32 \text{ V}, V_{GS} = 5 \text{ V}, I_D = 3.9 \text{ A}$	_	2.4		nC
	Gate-source charge 1		Q _{gs1}		_	1.0	_	
Cata quitab abarga	Gate-drain ("Miller") charge		Q _{gd}	$V_{DD} \simeq 32 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 3.9 \text{ A}$	_	0.8	_	
Gate switch charge — 1.5 —	Gate switch charge		Q _{SW}		_	1.3	_	

Source-Drain Ratings and Characteristics (Ta = 25°C)

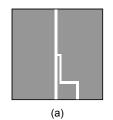
Characteristics		Symbol	Test Condition	Min	Тур.	Max	Unit
Pulse drain reverse current	(Note 1)	I _{DRP}	_	_	_	15.6	Α
Forward voltage (Diode)		V _{DSF}	I _{DR} = 3.9 A, V _{GS} = 0 V	_	_	-1.2	V

3

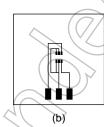
Note 1: Ensure that the channel temperature does not exceed 150°C.

Note 2: (a) Device mounted on a glass-epoxy board (a)

(b) Device mounted on a glass-epoxy board (b)



FR-4 $25.4\times25.4\times0.8$ Unit: (mm)

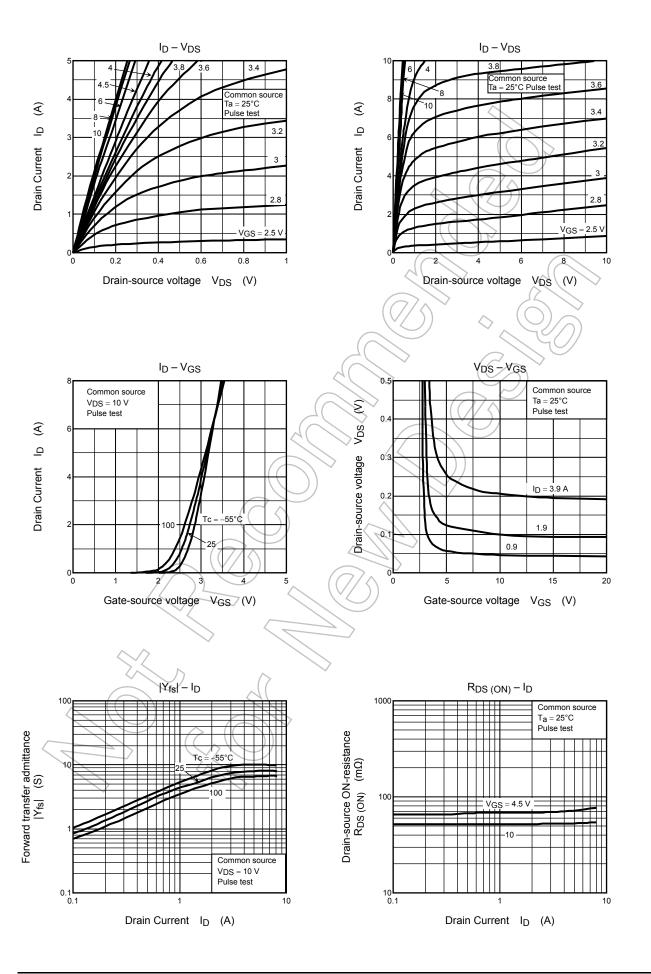


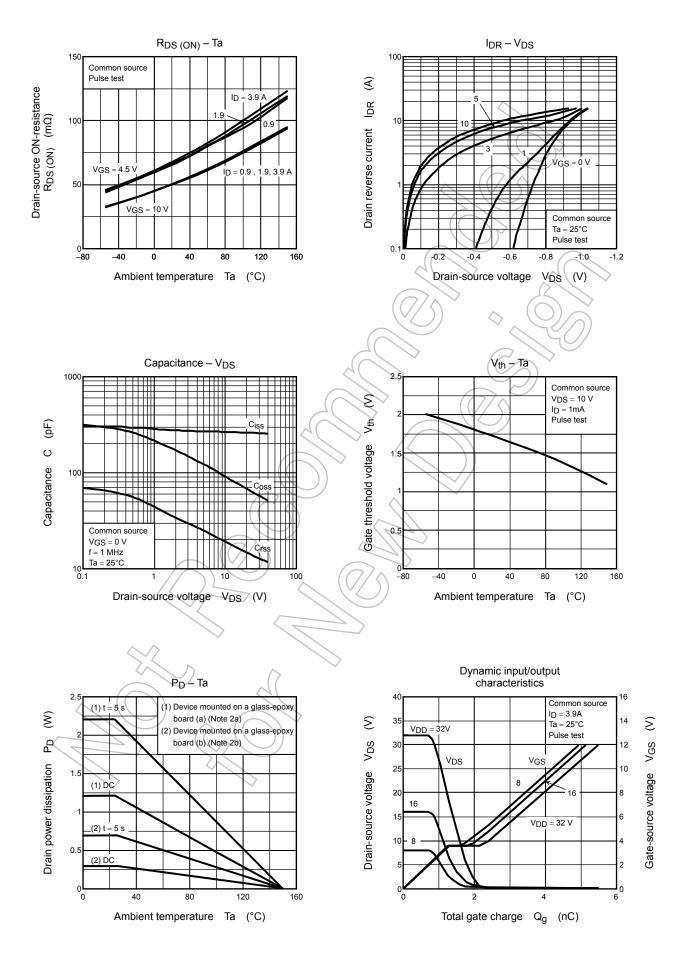
FR-4 25.4 × 25.4 × 0.8 Unit: (mm)

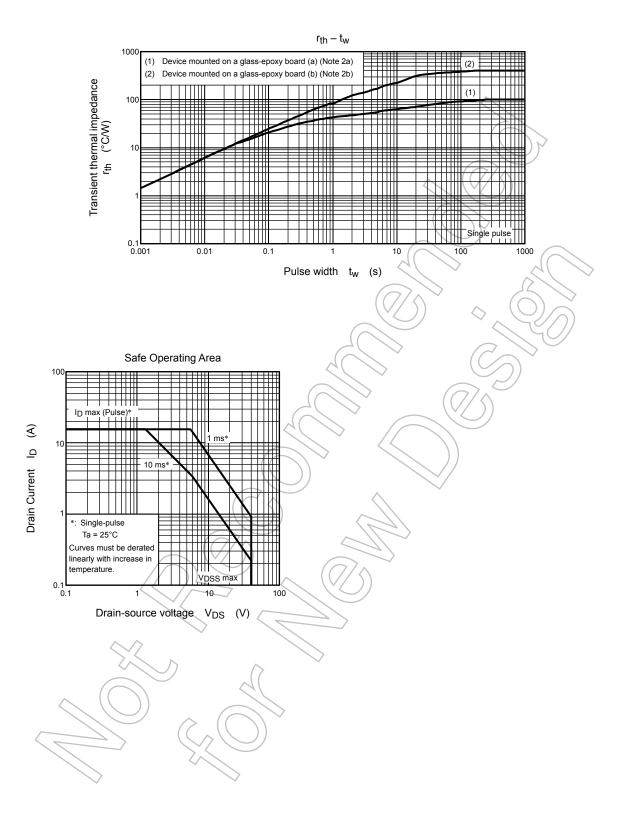
Note 3: $V_{DD}=24~V,~T_{ch}=25^{\circ}C$ (initial), L = 0.5 mH, R_G = 25 Ω , I_{AR} = 3.9 A

Note 4: Repetitive rating: pulse width limited by maximum channel temperature

Note 5: • on lower left of the marking indicates Pin 1.









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Handbook" etc.

20070701-EN

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